

Surface Mount Superfast Recovery Rectifier

FEATURES:

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

Circuit Diagram & Pin Configuration:





SMB/DO-214AA

Marking

Type number	Marking code
ES1AB	ES1A
ES1BB	ES1B
ES1CB	ES1C
ES1DB	ES1D
ES1EB	ES1E
ES1GB	ES1G
ES1JB	ES1J

Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

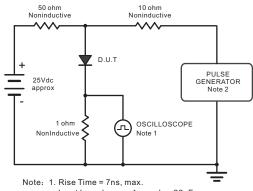
Parameter	Symbols	ES1AB	ES1BB	ES1CB	ES1DB	ES1EB	ES1GB	ES1JB	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	٧
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T_c = 125 °C	I _{F(AV)}	1							А
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I _{FSM}	30							А
Maximum Forward Voltage at 1 A	V _F	1 1.25 1.68					1.68	V	
Maximum DC Reverse Current $T_a = 25 ^{\circ}\text{C}$ at Rated DC Blocking Voltage $T_a = 125 ^{\circ}\text{C}$	I _R	5 100							μA
Typical Junction Capacitance at V _R =4V, f=1MHz	C _j	15							pF
Maximum Reverse Recovery Time (1)	t _{rr}	35							ns
Typical Thermal Resistance (2)	R _{θJA}	70							°C/W
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150							°C

^(1) Measured with I_{F} = 0.5 A, I_{R} = 1 A, I_{rr} = 0.25 A.

^(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



- Input Impedance = 1megohm,22pF.
 - 2. Ries Time =10ns, max. Source Impedance = 50 ohms.

+0.5

-1.0

10ns/div

Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

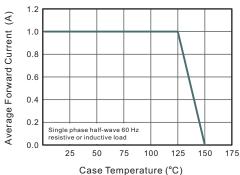


Fig.4 Typical Forward Characteristics

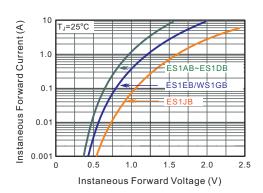


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current

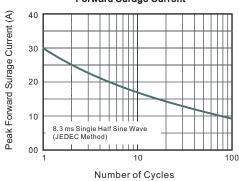


Fig.3 Typical Reverse Characteristics

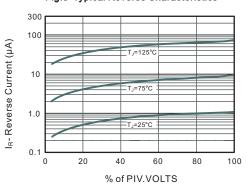
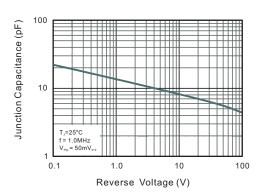


Fig.5 Typical Junction Capacitance

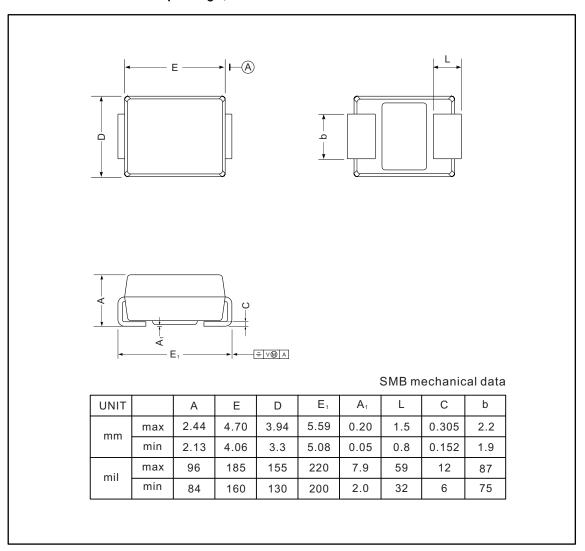




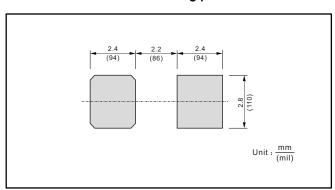
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMB/DO-214AA



The recommended mounting pad size





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